DATASHEET

Description

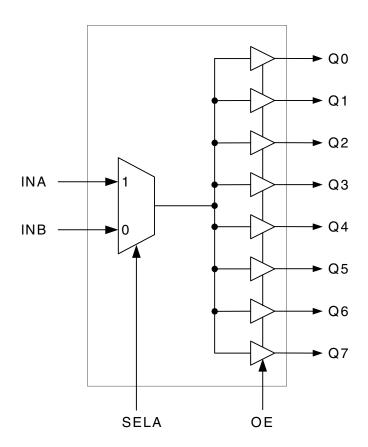
The 552-02S is a low skew, single-input to eight- output clock buffer. The device offers a dual input with pin select for switching between two clock sources. It has best in class Additive Phase Jitter of sub 50fsec

IDT makes many non-PLL and PLL based low skew output devices as well as Zero Delay Buffers to synchronize clocks. Contact us for all of your clocking needs.

Features

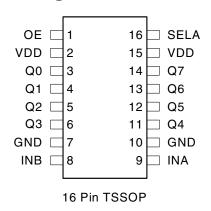
- Low RMS Additive Phase Jitter: 50fs
- Low output skew: 50ps
- Operating Voltages of 1.8V to 3.3V
- Packaged in 16-pin TSSOP and 16-pin VFQFN, Pb-free
- Input clock multiplexer simplifies clock selection
- Output Enable pin tri-states outputs
- Input/Output clock frequency up to 200 MHz
- Low power CMOS technology
- 3.3V tolerant inputs
- Extended temperature (-40°C to +105°C)

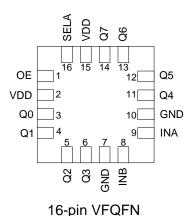
Block Diagram





Pin Assignments





Input Source Select

SELA	Input
0	INB
1	INA

Pin Descriptions

Pin	Pin	Pin	Pin Description
Number	Name	Type	
1	OE	Input	Output Enable. Tri-states outputs when low. Internal pull-up resistor.
2	VDD	Power	Connect to +1.8V, +2.5V or +3.3V. Must be the same as pin 15.
3	Q0	Output	Clock Output 0.
4	Q1	Output	Clock Output 1.
5	Q2	Output	Clock Output 2.
6	Q3	Output	Clock Output 3.
7	GND	Power	Connect to ground.
8	INB	Input	Clock Input B. 3.3V tolerant.
9	INA	Input	Clock Input A. 3.3V tolerant.
10	GND	Power	Connect to ground.
11	Q4	Output	Clock Output 4.
12	Q5	Output	Clock Output 5.
13	Q6	Output	Clock Output 6.
14	Q7	Output	Clock Output 7.
15	VDD	Power	Connect to +1.8V, +2.5V or +3.3V. Must be the same as pin 2.
16	SELA	Input	Selects either INA or INB. Internal pull-up resistor.

External Components

A minimum number of external components are required for proper operation. Decoupling capacitors of 0.01 μ F should be connected between VDD on pin 2 and GND on pin 7, and between VDD on pin 15 and GND on pin 10, as close to the device as possible. A 33 Ω series terminating resistor should be used on each clock output if the trace is longer than 1 inch.

To achieve the low output skews that the 552-02S is capable of, careful attention must be paid to board layout. Essentially, all 8 outputs must have identical terminations, identical loads, and identical trace geometries. If they do not, the output skew will be degraded. For example, using a 30Ω series termination on one output (with 33Ω on the others) will cause at least 15ps of skew.



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 552-02S. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.465V
All Inputs and Outputs	-0.5 V to 3.465V
Ambient Operating Temperature, Extended	-40 to +105°C
Storage Temperature	-65 to +150 °C
Junction Temperature	175 °C
Soldering Temperature	260 °C

Recommended Operation Conditions

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature, Extended	-40	-	+105	°C
Power Supply Voltage (measured in respect to GND)	+1.71		+3.465	V



DC Electrical Characteristics

VDD=1.8 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, INA, INB	V _{IH}	Note 1	0.7xVDD		1.89	V
Input Low Voltage, INA, INB	V _{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V _{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -10 mA	1.3			V
Output Low Voltage	V _{OL}	I _{OL} = 10 mA			0.35	V
Operating Supply Current	IDD	No load, 135 MHz		32		mA

VDD=2.5 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, INA, INB	V _{IH}	Note 1	0.7xVDD		2.625	V
Input Low Voltage, INA, INB	V _{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V _{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -16 mA	1.8			V
Output Low Voltage	V _{OL}	I _{OL} = 16 mA			0.5	V
Operating Supply Current	IDD	No load, 135 MHz		43		mA

VDD=3.3 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.135		3.465	V
Input High Voltage, INA, INB	V _{IH}	Note 1	0.7xVDD		3.465	V
Input Low Voltage, INA, INB	V _{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V _{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -25 mA	2.2			V
Output Low Voltage	V _{OL}	I _{OH} = 25 mA			0.7	V
Operating Supply Current	IDD	No load, 135 MHz		55		mA



AC Electrical Characteristics

VDD = 1.8V ±5%, Ambient Temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.36 to 1.44 V, C _L =5 pF		1	1.5	ns
Output Fall Time	t _{OF}	1.44 to 0.36 V, C _L =5 pF		1	1.5	ns
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.5	3	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

VDD = 2.5V ±5%, Ambient Temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.5 to 2.0 V, C _L =5 pF		0.6	1.0	ns
Output Fall Time	t _{OF}	2.0 to 0.5 V, C _L =5 pF		0.6	1.0	ns
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.7	3.5	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

VDD = 3.3V ±5%, Ambient Temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.66 to 2.64 V, C _L =5 pF		0.6	1.0	ns
Output Fall Time	t _{OF}	2.64 to 0.66 V, C _L =5 pF		0.6	1.0	ns
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.5	3	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

Notes:

- With rail-to-rail input clock.

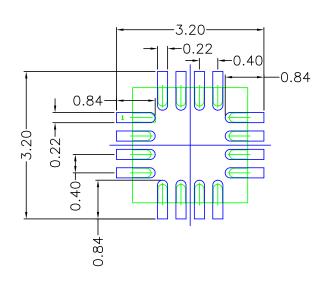
- 2. Between any two outputs with equal loading.
 3. Propagation delay matching through the part.
 4. Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

	₹ENESΔS	
WO		REVISIONS
Ş	■	REV DESCRIPTION
E₩	■	00 INITIAL RELEASE 01 ADD PIN1 CHAMFER
LOW SKEW 2-INPUT MUX AND 1 TO 8 CLOCK BUFFER	Pin 1 Dot By Marking 2.50±0.05	1.20Ref - 0.50±0.10 0.40±0.10 0.50±0.02 0.50±0.02
6	0.000-0.050	TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR X± ±1' XXX± XXX± APPROVALS DATE DRAWN 9% 04/03/14 CHECKED

DO NOT SCALE DRAWING

RENESAS

	REVISIONS
REV	DESCRIPTION
00	INITIAL RELEASE
01	ADD PIN1 CHAMFER

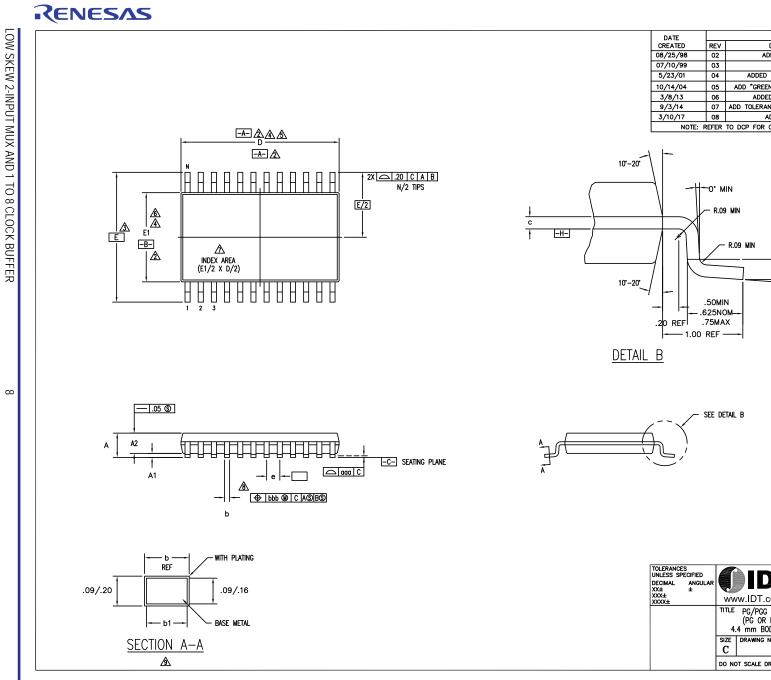


RECOMMENDED LAND PATTERN DIMENSION

NOTES:

- 1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW AS VIEWED ON PCB.
 3. COMPONENT OUTLINE IS SHOWN FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
- 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPEC DECIMAL X± XX± XXX±		www.IDT.cor						
APPROVALS	DATE	TITLE	CMG 16 P.					
DRAWN JH	04/03/14		2.5 x 2.5					
CHECKED			0.40 mm					
		SIZE	DRAWING No.					
		\circ	Р					
		DO NO	OT SCALE DRAW					



RENESAS

	DATE		
	CREATED	REV	
	08/25/98	02	Al
ı	07/10/99	03	
	5/23/01	04	ADDED
	10/14/04	05	ADD "GREE
	3/8/13	06	ADDE
	9/3/14	07	ADD TOLERA
	3/10/17	08	
ı	NOTE: F	REFER	TO DCP FOR

		PG/P	GG8			PG/P	GG14		PG/PGG16		PG/PGG20			PG/PGG24				PG/PGG28					
S	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIATI	ION
M B		AA		무		AB-1		₽		AB] 무		AC		- 무		AD] 🛾 [ΑE	
2	MIN	NOM	MAX	É	MIN	NOM	MAX	Ė	MIN	NOM	MAX	Ė	MIN	NOM	MAX	É	MIN	NOM	MAX] Ė	MIN	NOM	MAX
Α	.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20
A1	.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15
A2	.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05
D	2.90	3.00	3.10	4,5	4.90	5.00	5.10	4,5	4.90	5.00	5.10	4,5	6.40	6.50	6.60	4,5	7.70	7.80	7.90	4,5	9.60	9.70	9.80
Ε	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60
E1	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50
е		.65 BSC				.65 BSC				.65 BSC				.65 BSC				.65 BSC				.65 BSC	
b	.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30
b1	.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25
aaa	_	_	.10		-	_	.10		_	_	.10		_	_	.10		_	_	.10			-	.10
bbb	_	-	.10		-	_	.10		_	_	.10		_	-	.10		_	_	.10		_	-	.10
N		8				14				16				20				24				28	

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- DATUMS —A— AND —B— TO BE DETERMINED AT DATUM PLANE —H—
- DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE

	OPTION T1						
		PGG14	IT1				
S Y M B	JEDE	C VARIAT	ION	N			
B		AB-1		N T E			
2	MIN	NOM	MAX	Ė			
Α	.90	1.10	1.20				
A1	.05	.10	.15				
A2	.80	1.00	1.05				
D	4.90	5.00	5.10	4,5			
Ε	6.20	6.40	6.60	3			
E1	4.30	4.40	4.50	4,6			
е		.65 BSC					
b	.19	.25	.30				
b1	.19	.22	.25				
С	.09	-	.20				
aaa	ı	-	.10				
bbb	_	_	.10				
N		14					

TOLERANCES
UNLESS SPECIFIED
DECIMAL ANGULAR
XX± ±
XXX±
XXXX±



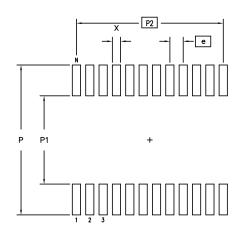
TITLE PG/PGG
(PG OR
4.4 mm BC

DO NOT SCALE I

RENESAS

DATE		
CREATED	REV	
08/25/98	02	
07/10/99	03	
5/23/01	04	ADDE
10/14/04	05	ADD "GRI
3/8/13	06	ADI
9/3/14	07	ADD TOLER
3/10/17	08	
NOTE: F	REFER	TO DCP FOR

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
Р	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40
P1	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40
P2	1.95	BSC	3.90 BSC		4.55 BSC		5.85 BSC		7.15 BSC		8.45 BSC	
X	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50
е	.65 [BSC	.65 E	.65 BSC		.65 BSC		.65 BSC		BSC BSC	.65 BSC	
N		3	14		16		20		24		28	

TOLERANCE: UNLESS SPI			
DECIMAL XX±	ANGULAR ±		7
XXX± XXXX±		ww	w.II
		TITLE	PG,
		١.	(PC
		4.	4 m
		SIZE	DRA
		C	

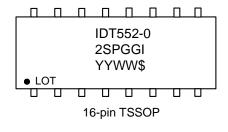


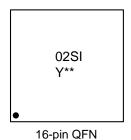
Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
552-02SPGGI		Tubes	16-pin TSSOP	-40°C to +105°C
552-02SPGGI8	TBD	Tape and Reel	16-pin TSSOP	-40°C to +105°C
552-02SCMGI		Tubes	16-pin VFQFN	-40°C to +105°C
552-02SCMGI8		Tape and Reel	16-pin VFQFN	-40°C to +105°C

[&]quot;G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

Marking Diagrams





Notes:

- 1. "**" is the lot sequence.
- 2. "YYWW" or "Y" is the last digit(s) of the year and week that the part was assembled.
- 3. "\$" denotes the mark code.
- 4. "LOT" denotes lot number.
- 5. "G" after the two-letter package code denotes RoHS compliant package.
- 6. "I" denotes extended temperature range device.
- 7. Bottom marking: country of origin (TSSOP only).

Revision History

Rev.	Date	Originator	Description of Change
В	04/18/17	C.P.	 Replaced package outline drawings with latest CMG16 and PGG16 versions. Updated legal disclaimer.
Α	07/11/16	H.G.	Release to final.



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(Rev.1.0 Mar 2020)

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PI6C4931502-04LIE NB7L1008MNG NB7L14MN1G PI49FCT20807QE PI6C4931502-04LIEX ZL80002QAB1 PI6C4931504-04LIEX
PI6C10806BLEX ZL40226LDG1 ZL40219LDG1 8T73S208B-01NLGI SY75578LMG PI49FCT32805QEX PL133-27GC-R
CDCV304PWG4 MC10LVEP11DG MC10EP11DTG MC100LVEP11DG MC100E111FNG MC100EP11DTG NB6N11SMNG
NB7L14MMNG NB3N2304NZDTR2G NB6L11MMNG NB6L14MMNR2G NB6L611MNG PL123-02NGI-R NB3N111KMNR4G
ADCLK944BCPZ-R7 ZL40217LDG1 NB7LQ572MNG HMC940LC4BTR ADCLK946BCPZ-REEL7 ADCLK946BCPZ
ADCLK846BCPZ-REEL7